EAST Search History

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
S1	12770	plating with insulating	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/09/13 11:02
S2	2578	S1 and plating with hole with insulating	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/09/13 11:02
S3	1356	S2 and plating with through with hole with insulating	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/09/13 11:03
S4	701	S2 and plating with through with hole with insulating with surface	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/12/24 22:45
S5	701	plating with through with hole with insulating with surface	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/09/13 11:04
S6	215	plating with through with hole with insulating with surface with inner	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/09/13 11:04
S7	33	S6 and plating adj solution	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/09/13 11:20
S8	22	"4547836"	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/09/13 11:20

S9	40	("20020057099" | "20050186791" | "20070190785" | "4547836" | "5166097" | "5166097" | "5321841" | "5487218" | "5961593" | "6067623" | "6090474" | "6190834" | "6221769" | "6221769" | "6338064" | "6410976" | "6458696" | "6458696" | "6479382" | "6604198" | "6747465" | "6795967" | "6802000").PN.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/12/24 22:46
S10	8	"6190834"	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/12/24 22:54
S11	22	"4547836"	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/12/24 22:54
S12	13196	plating with insulating	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/02/15 16:53
S13	2687	S12 and plating with hole with insulating	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/02/15 16:53
S14	1407	S13 and plating with through with hole with insulating	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/02/15 16:53
S15	735	S13 and plating with through with hole with insulating with surface	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/02/15 16:53

S16	735	plating with through with hole with insulating with surface	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/02/15 16:53
S17	228	plating with through with hole with insulating with surface with inner	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/02/15 16:53
S18	35	S17 and plating adj solution	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/02/15 16:53
S19	22	"4547836"	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/02/15 16:53
S20	40	("20020057099" | "20050186791" | "20070190785" | "4547836" | "5166097" | "5166097" | "5321841" | "5487218" | "5961593" | "6067623" | "6090474" | "6190834" | "6221769" | "6221769" | "6338064" | "6410976" | "6458696" | "6458696" | "6479382" | "6604198" | "6747465" | "6795967" | "6802000").PN.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/02/15 16:53
S21	8	"6190834"	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/02/15 16:53
S22	22	"4547836"	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/02/15 16:53

S23	13260	S12 S13 S14 S15 S16 S17 S18 S19 S20 S21 S22	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/02/15 16:53
S24	13681	plating with insulating	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/07/06 06:26
S25	2826	S24 and plating with hole with insulating	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/07/06 06:26
S26	1479	S25 and plating with through with hole with insulating	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/07/06 06:26
S27	772	S25 and plating with through with hole with insulating with surface	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/07/06 06:26
S28	772	plating with through with hole with insulating with surface	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/07/06 06:26
S29	238	plating with through with hole with insulating with surface with inner	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/07/06 06:26
S30	38	S29 and plating adj solution	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/07/06 06:26
S31	22	"4547836"	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/07/06 06:26

S32	40	("20020057099" | "20050186791" | "20070190785" | "4547836" | "5166097" | "5166097" | "5321841" | "5487218" | "5961593" | "6067623" | "6090474" | "6190834" | "6221769" | "6221769" | "6338064" | "6410976" | "6458696" | "6458696" | "6479382" | "6604198" | "6747465" | "6795967" | "6802000").PN.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/07/06 06:26
S33	8	"6190834"	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/07/06 06:26
S34	22	"4547836"	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/07/06 06:26
S35	13681	plating with insulating	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/07/06 06:26
S36	2826	S35 and plating with hole with insulating	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/07/06 06:26
S37	1479	S36 and plating with through with hole with insulating	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/07/06 06:26
S38	772	S36 and plating with through with hole with insulating with surface	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/07/06 06:26

S39	772	plating with through with hole with insulating with surface	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/07/06 06:26
S40	238	plating with through with hole with insulating with surface with inner	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/07/06 06:26
S41	38	S40 and plating adj solution	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/07/06 06:26
S42	22	"4547836"	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/07/06 06:26
S43	40	("20020057099" | "20050186791" | "20070190785" | "4547836" | "5166097" | "5166097" | "5321841" | "5487218" | "5961593" | "6067623" | "6090474" | "6190834" | "6221769" | "6221769" | "6338064" | "6410976" | "6458696" | "6458696" | "6479382" | "6604198" | "6747465" | "6795967" | "6802000").PN.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/07/06 06:26
S44	8	"6190834"	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/07/06 06:26
S45	22	"4547836"	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/07/06 06:26

S46	13745	S35 S36 S37 S38 S39 S40 S41 S42 S43 S44 S45	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/07/06 06:26
S47	13745	S24 S25 S26 S27 S28 S29 S30 S31 S32 S33 S34 S35 S36 S37 S38 S39 S40 S41 S42 S43 S44 S45 S46	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/07/06 06:26
S48	11	("20040089557" | "3158499" | "3886053" | "4396467").PN.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/07/06 06:46
S49	22	"4547836"	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/07/06 07:28
S50	174	205/281.ccls.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/07/06 07:35
S51	585	205/291.ccls.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/07/06 07:37
S52	28	S25 and plating with through with hole with semiconductor adj substrate	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/07/06 07:37
S53	2	S52 and (forc$3 with plat$3 with solution with (hole or via or opening))	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/07/06 07:38
S54	1510	(forc$3 with plat$3 with solution with (hole or via or opening))	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/07/06 07:41

S55	8	S54 and (semiconductor adj substrate with (via or hole or opening))	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/07/06 07:42
S56	5677	(press$3 with plat$3 with solution with (hole or via or opening))	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/07/06 07:44
S57	20	S56 and (semiconductor adj substrate with (via or hole or opening))	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/07/06 07:45
S58	501	438/667.ccls.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/07/06 16:58
S59	1114	438/629.ccls.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/07/06 16:59
S60	484	438/674.ccls.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/07/06 17:01
S61	0	S58 and plating with through with hole with insulating with surface with inner	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/07/06 17:02
S62	8	S58 and plating with through with hole with insulating	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/07/06 17:02
S63	7	S59 and plating with through with hole with insulating	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/07/06 17:02

| S64 | 3 | S60 and plating with through with hole with insulating | US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2008/07/06 17:03 |

7/6/08 9:19:20 PM
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